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Hex Inverters



ADE-205-242A (Z)

2nd. Edition Jul. 2001

Description

The HD74LV04A has six imverters in a 14-pin package.

Low-voltage and high-speed operation is suitable for the battery-powered products (e.g., notebook computers), and the low-power consumption extends the battery life.

Features

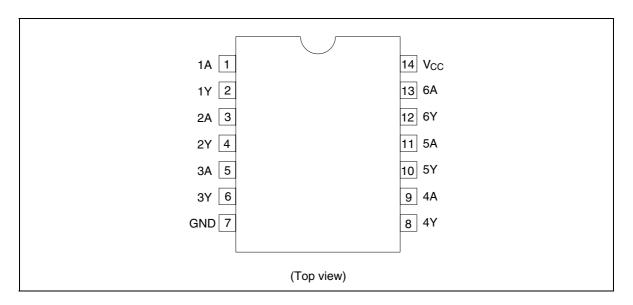
- $V_{cc} = 2.0 \text{ V}$ to 5.5 V operation
- All inputs V_{IH} (Max.) = 5.5 V (@ V_{CC} = 0 V to 5.5 V)
- All outputs V_0 (Max.) = 5.5 V (@ V_{cc} = 0 V)
- Typical V_{OL} ground bounce < 0.8 V (@ V_{CC} = 3.3 V, Ta = 25°C)
- Typical V_{OH} undershoot > 2.3 V (@ V_{CC} = 3.3 V, Ta = 25°C)
- Output current $\pm 6 \text{ mA}$ (@V_{CC} = 3.0 V to 3.6 V), $\pm 12 \text{ mA}$ (@V_{CC} = 4.5 V to 5.5 V)

Function Table

Input A	Output Y
Н	L
L	Н

Note: H: High level L: Low level

Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage range	V _{cc}	-0.5 to 7.0	V	
Input voltage range*1	V,	-0.5 to 7.0	V	
Output voltage range*1,2	V _o	$-0.5 \text{ to V}_{cc} + 0.5$	V	Output: H or L
		-0.5 to 7.0	_	V _{cc} : OFF
Input clamp current	I _{IK}	-20	mA	V ₁ < 0
Output clamp current	I _{ok}	±50	mA	$V_{o} < 0 \text{ or } V_{o} > V_{cc}$
Continuous output current	I _o	±25	mA	$V_o = 0$ to V_{cc}
Continuous current through V_{cc} or GND	$I_{\rm cc}$ or $I_{\rm GND}$	±50	mA	
Maximum power dissipation at Ta = 25°C (in still air) *3	P _T	785	mW	SOP
		500	=	TSSOP
Storage temperature	Tstg	-65 to 150	°C	

Notes: The absolute maximum ratings are values which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

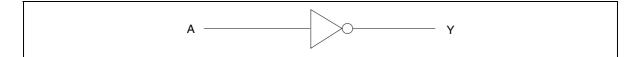
- 1. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- 2. This value is limited to 5.5 V maximum.
- 3. The maximum package power dissipation was calculated using a junction temperature of 150°C.

Recommended Operating Conditions

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage range	V _{cc}	2.0	5.5	V	
Input voltage range	V _i	0	5.5	V	
Output voltage range	V _o	0	V _{cc}	V	
Output current	I _{OH}	_	-50	μΑ	V _{cc} = 2.0 V
		_	-2	mA	$V_{cc} = 2.3 \text{ to } 2.7 \text{ V}$
		_	-6		$V_{cc} = 3.0 \text{ to } 3.6 \text{ V}$
		_	-12		$V_{cc} = 4.5 \text{ to } 5.5 \text{ V}$
	I _{OL}	_	50	μΑ	V _{cc} = 2.0 V
		_	2	mA	$V_{cc} = 2.3 \text{ to } 2.7 \text{ V}$
		_	6		$V_{cc} = 3.0 \text{ to } 3.6 \text{ V}$
		_	12		$V_{cc} = 4.5 \text{ to } 5.5 \text{ V}$
Input transition rise or fall rate	Δt/Δν	0	200	ns/V	$V_{cc} = 2.3 \text{ to } 2.7 \text{ V}$
		0	100		$V_{cc} = 3.0 \text{ to } 3.6 \text{ V}$
		0	20		$V_{cc} = 4.5 \text{ to } 5.5 \text{ V}$
Operating free-air temperature	Та	-40	85	°C	

Note: Unused or floating inputs must be held high or low.

Logic Diagram



DC Electrical Characteristics

 $Ta = -40 \text{ to } 85^{\circ}\text{C}$

Item	Symbol	V _{cc} (V)*	Min	Тур	Max	Unit	Test Conditions
Input voltage	V _{IH}	2.0	1.5	_	_	٧	
		2.3 to 2.7	$V_{cc} \times 0.7$	_	_	_	
		3.0 to 3.6	$V_{cc} \times 0.7$	_	_		
		4.5 to 5.5	$V_{cc} \times 0.7$	_	_		
	V _{IL}	2.0	_	_	0.5	_	
		2.3 to 2.7	_	_	$V_{cc} \times 0.3$	_	
		3.0 to 3.6	_	_	$V_{cc} \times 0.3$	_	
		4.5 to 5.5	_	_	$V_{cc} \times 0.3$	_	
Output voltage	V _{OH}	Min to Max	V _{cc} - 0.1	_	_	V	$I_{OH} = -50 \mu A$
		2.3	2.0	_	_		I _{OH} = -2 mA
		3.0	2.48	_	_		I _{OH} = -6 mA
		4.5	3.8	_	_		I _{OH} = -12 mA
	V _{oL}	Min to Max	_	_	0.1	_	Ι _{οι} = 50 μΑ
		2.3	_	_	0.4	_	I _{OL} = 2 mA
		3.0	_	_	0.44	_	I _{oL} = 6 mA
		4.5	_	_	0.55	_	I _{OL} = 12 mA
Input current	I _{IN}	0 to 5.5	_	_	±1	μΑ	V _{IN} = 5.5 V or GND
Quiescent supply current	I _{cc}	5.5	_	_	20	μА	$V_{IN} = V_{CC}$ or GND, $I_{O} = 0$
Output leakage current	I _{OFF}	0	_	_	5	μА	$V_{_{\rm I}}$ or $V_{_{\rm O}}$ = 0 V to 5.5 V
Input capacitance	C _{IN}	3.3	_	2.3	_	pF	$V_{I} = V_{CC}$ or GND

Note: For conditions shown as Min or Max, use the appropriate values under recommended operating conditions.

Switching Characteristics

 $V_{cc} = 2.5 \pm 0.2 \text{ V}$

		1a = 1	25°C		1a = - 85°C	40 to				
Item	Symbol	Min	Тур	Max	Min	Max	_ Unit	Test Conditions	FROM (Input)	TO (Output)
Propagation	t _{PLH}	_	8.0	11.7	1.0	14.0	ns	C _L = 15 pF	Α	Υ
delay time	t _{PHL}	_	11.2	15.5	1.0	18.0		C _L = 50 pF	-	

 $V_{cc} = 3.3 \pm 0.3 \text{ V}$

		Ta = 1	25°C		Ta = 85°C	40 to				
Item	Symbol	Min	Тур	Max	Min	Max	Unit	Test Conditions	FROM (Input)	TO (Output)
Propagation	t _{plH}	_	5.6	7.1	1.0	8.5	ns	C _L = 15 pF	Α	Υ
delay time	$t_{_{\mathrm{PHL}}}$	_	8.0	10.6	1.0	12.0	_	C _L = 50 pF	="	

 $V_{cc} = 5.0 \pm 0.5 \text{ V}$

					85°C					
Item	Symbol	Min	Тур	Max	Min	Max	Unit	Test Conditions	FROM (Input)	TO (Output)
Propagation	t _{PLH}	_	3.8	5.5	1.0	6.5	ns	C _L = 15 pF	Α	Υ
delay time	$t_{_{PHL}}$	_	5.5	7.5	1.0	8.5		C _L = 50 pF		

Ta = -40 to

Ta = 25°C

Operating Characteristics

 $C_L = 50 \text{ pF}$

Ta =	: 25°C
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Item	Symbol	$V_{cc}(V)$	Min	Тур	Max	Unit	Test Conditions
Power dissipation capacitance	C_{\scriptscriptstylePD}	3.3	_	9.6	_	pF	f = 10 MHz
		5.0	_	11.4	_		

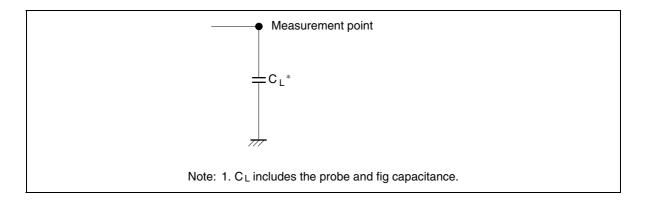
Noise Characteristics

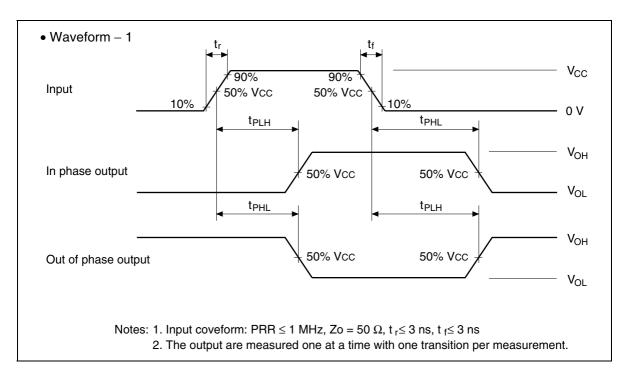
 $C_L = 50 \text{ pF}$

Ta	= 2	25°	С
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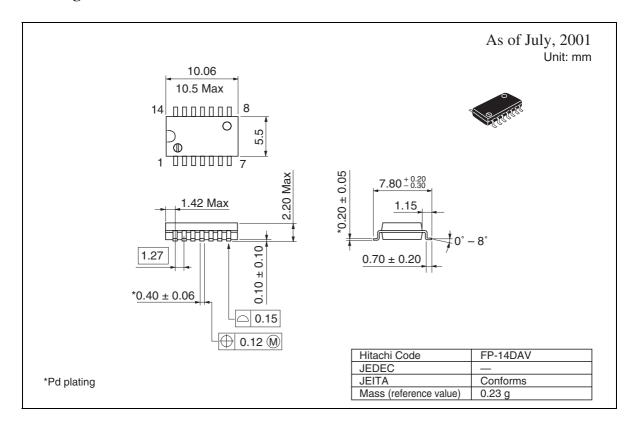
Item	Symbol	V_{cc} (V)	Min	Тур	Max	Unit	Test Conditions
Quiet output, maximum dynamic V _{oL}	$V_{OL(P)}$	3.3	_	0.26	0.8	V	
Quiet output, minimum dynamic V _{oL}	V _{OL (V)}	3.3	_	-0.1	-0.8	_	
Quiet output, minimum dynamic V _{он}	V _{OH (V)}	3.3	_	3.1	_	_	
High-level dynamic input voltage	V _{IH (D)}	3.3	2.31	_	_	V	
Low-level dynamic inout voltage	V _{IL (D)}	3.3	_	_	0.99	_	

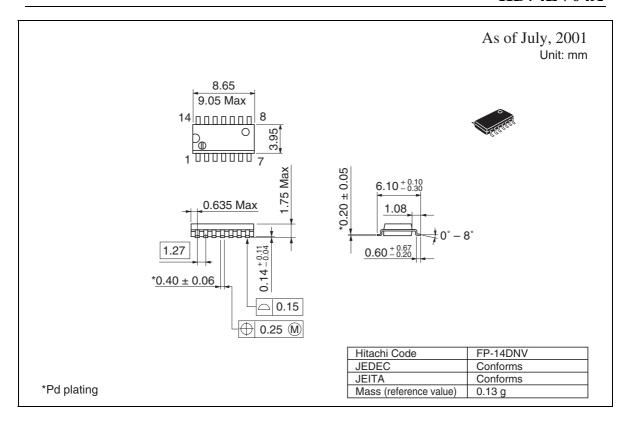
Test Circuit

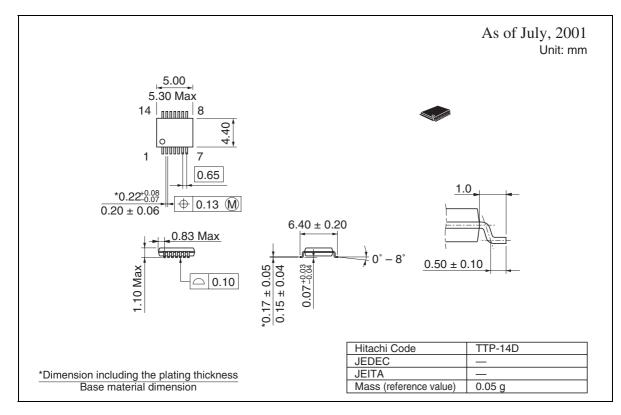




Package Dimensions







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